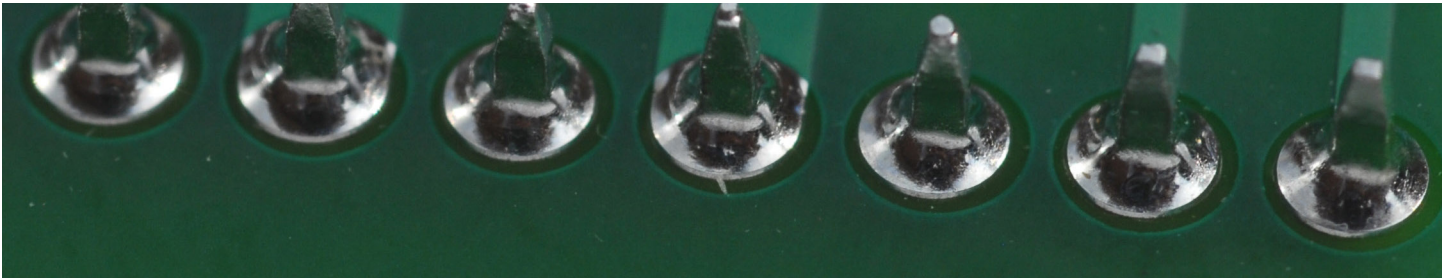


# K100LD

**THE LOW-COST ALLOY WITH  
SUPERIOR HOLE-FILL**



## K100LD: THE HIGH PERFORMANCE AND SILVER-FREE ALLOY

- Lowest Dissolution of Copper
  - Prevents copper erosion and yields consistent soldering results
- Low Defects
  - Designed to give excellent wetting to through-hole and bottom-side SMT components
  - Dopants in K100LD promote fluidity and proper surface tension to yield good hole-fill without bridges
- Low Dross
  - Dross-reducing technology results in 20% lower dross formation
- Low Dollars
  - Lower cost than SAC305
- Low Dullness
  - Produces shiny, smooth solder joints

### Alloy Properties Comparing K100LD with SAC305

		K100LD	SAC305
<b>Composition</b>	Tin %	~99.3	96.5
	Silver %	0	3.0
	Copper %	0.7	0.5
	Contains Nickel	Yes	No
	Contains Bismuth	Yes	No
<b>Physical Properties</b>	Melt Point	~227°C	217-220°C
	Pasty Range	0	3°C
	Appearance	Shiny	Dull
	Shrink Holes	No	Yes
<b>Solder Pot</b>	Copper Dissolution (Sn63=1)	0.8	2.1
	Pot Management	Easiest	Difficult
	Reactivity to Equipment	Low	High
	Suggested Pot Temperature	255-270°C	250-260°C
	Approximate Relative Cost (Sn63=1)	1.5	3.0

### K100LD Offerings:

Preforms  
Cored Wire

Solid Wire  
Bar